



**AI TECHNOLOGY INC**  
 70 Washington Road  
 Princeton Jct., NJ 08550  
 (609) 799-9388 fax (609) 799-9308  
 E-Mail: [ait@aitechnology.com](mailto:ait@aitechnology.com)  
 Internet: <http://www.aitechnology.com>

**High Strength**  
**RAPID CURING**  
**100% Solid**  
**Insulating**  
**Epoxy Paste Adhesive**  
**IDEAL FOR:**  
 Rapid curing at elevated temperature  
 Die-Attach  
 Automated Assembly

**DESCRIPTION:**

ME7630-RC is a RAPID CURING insulating epoxy adhesive for snap-curing applications. This thixotropic paste is solvent free. (TI is approx. 2). It is designed for automated, inline bonding processing.

ME7630-RC is low in ionic impurities (<80 ppm total) and meets all requirements for MIL-Std 883; Method 5011.5 specification for dielectric adhesive. Fast curing can be achieved from 80°C and higher temperatures.

**AVAILABILITY:**

ME7630-RC is available in syringes for automatic needle dispense applications or in jars.

**APPLICATION PROCEDURES:**

- ( 1 ) Thaw for 30 minutes before opening jar or using syringes.
- ( 2 ) Dispense adhesive onto clean substrate with a suitable pattern to assure full die coverage.
- ( 3 ) Cure according to one of the recommended cure schedules.

**CAUTION:** This product may cause skin irritation. Avoid skin contact. If contact does occur, wash immediately with soap and water. Please refer SDS for more details.  
 The information contained herein is believed to be reliable. All recommendations or suggestions are made without guarantee inasmuch as conditions and methods of commercial use are beyond our control. Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is to be used in manufacturing and in the final product. Under no circumstance shall AI Technology be liable for accidental, consequential or other damages arising from the use or handling of this product.

While AI Technology owns all proprietary rights of material formulations of its products, specific usage in the manufacturing of certain products may involve patent rights of other companies.

**PRIMA-BOND**  
**ME7630-RC**

**TYPICAL PROPERTIES\***

Electrical Resistivity ( 150°C/ 8 min )	>1x10 <sup>14</sup> ohm-cm
Dielectric Strength (Volts/mil)	>750
Glass Transition Temp.(°C)	80 ±10%
Current Carrying Capabilities	
Lap-Shear Strength	>1500 psi >10.3 N/mm <sup>2</sup>
Device Push-off Strength	>3000 psi >20.6 N/mm <sup>2</sup>
Hardness (Type)	80 ( D ) ±10%
Cured Density (gm/cc)	1.2 ±10%
Thermal Conductivity	1.4 Btu-in/hr-ft <sup>2</sup> -°F ±10% 0.2 W/m-°C ±10%
Linear Thermal Expansion	40 ±15%
Coeff. (ppm/°C)	
Maximum Continuous Operation Temp. (°C)	<150
Pot Life	2 days
Avg. Viscosity(5 rpm, 25°C) (Brookfield DV-1, Spindle CP51)	17,000 cp ±20%
Thixotropic Index	

\* Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is intended to be used in manufacturing and in the final product.

**CURE SCHEDULES:**

<u>Temperature</u>	<u>Time</u>	<u>Pressure</u>
80°C	80 min	
125°C	20 min	
150°C	10 min	

Pot life is 2 days @ 25°C

**SHELF LIFE:**

<u>Storage temperature</u>	<u>Shelf Life</u>
-40°C	1 yr
25°C	2 days